

Patent Abstracts of Japan

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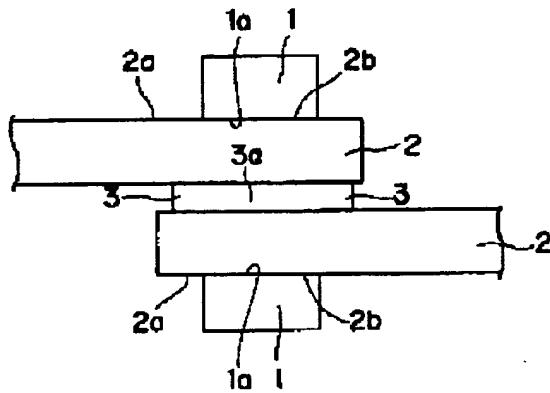
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APPLICANT : NIPPON PAINT CO LTD;

INVENTOR : KUSHIMA HIDEO;

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TITLE : METHOD FOR BONDING METALLIC PLATE



ABSTRACT : PURPOSE: To provide a method for bonding a metallic plate by which appearance, rigidity and vibration damping properties can greatly be improved while maintaining the conventional productivity in assembling a structure made of a metal.

CONSTITUTION: An electrically conductive structural adhesive 3 having a volume resistivity within the range of 10^0 to $10^{10} \Omega \cdot \text{cm}$ and a thickness within the range of 5 to $200 \mu\text{m}$ is formed in a space 3a between bonding parts of two metallic units 2 which are adherends and an electric current at a value within the range of 20 to 80% based on that required for welding of the mutual metallic units of the adherends is passed through the bonding parts to cure the structural adhesive by generation of heat in the metallic units by electric conduction.

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